IC149 Series (SMT)

QFP/TQFP - 176 Pins (44x44) 0.5mm pitch

Specifications

Insulation Resistance: $500 M\Omega$ at 150V DC

Withstanding Voltage: $100V_{eff}$ to $700V_{eff}$ for 1 minute Contact Resistance: $30 m\Omega$ max. at 10 mA and 20 mV

Operating Temp. Range: -25°C to +85°C 220°C for 60 seconds Reflow-soldering Temp.: Mating Cycles: 20 insertions maximum

Solvent Durability:

Allowable Torque (max.): - for 1-time screw connection = max 0.147 Nm

- for repetitive screw connection = min 0.078 Nm

max 0.098 Nm

Materials and Finish

Housing: Polyphenylenesulfide (PPS) glass filled UL94V-0

Contact: Beryllium Copper (BeCu)

Plating: Au $0.3\mu m$ min. over $2.5 \sim 4.5\mu m$ Ni = B5

Part Number (for IC-use)

IC149 176 - *66 - B5

Series No. No. of Contact Pins

Positioning Pins:

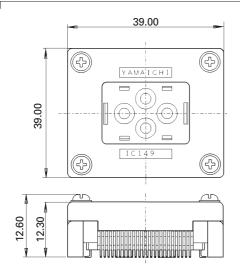
0 = Without Pins 1 = With Pins

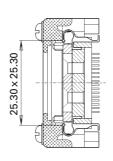
Contact Plating:

B5 = Au over Ni

Compatible Emulation-Adapter not available

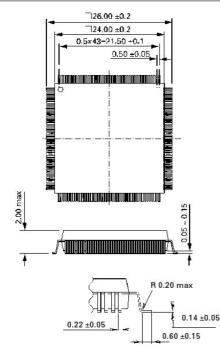
Outline Socket Dimensions (Reference Only)





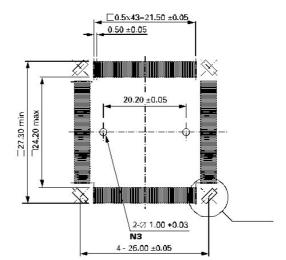
- 1. Ensure a clean contact area. Fluxes, dust and other impurifications may cause corrosion and contact problems.
- 2. This Socket is not for automatic production. It is particulary suitable for the development of software stored in ROM and for testing LSI-IC's.
- 3. Careful attention must be taken when fixing the Socket, since it is entirely made from thermoplastic material. If the max, torque is exceeded, the Socket will be damaged beyond repair.
- 4. If using the Socket with an Adapter, please use the gold-plated Socket

IC - Dimensions



Socket PCB-Layout

Top View from Socket



- N1: Metal soldering Tab Clip. Socket may be stabilized
- by soldering (Reflow) in these 4 areas.
- N3: These holes are only necessary for use with positioning pins.



IC149 Series (SMT)

QFP/TQFP - 272 Pins (68x68) 0.5mm pitch

Specifications

Insulation Resistance: $500 M\Omega$ at 150V DC

Withstanding Voltage: $100V_{\rm eff}$ to $700V_{\rm eff}$ for 1 minute Contact Resistance: $30m\Omega$ max. at 10mA and 20mV

Operating Temp. Range: -25°C to +85°C 220°C for 60 seconds Reflow-soldering Temp.: Mating Cycles: 20 insertions maximum

Solvent Durability:

Allowable Torque (max.): - for 1-time screw connection = max 0.147 Nm

- for repetitive screw connection = min 0.078 Nm max 0.098 Nm

Materials and Finish

Housing: Polyphenylenesulfide (PPS) glass filled UL94V-0

Contact: Beryllium Copper (BeCu)

Au $0.3\mu m$ min. over $2.5 \sim 4.5\mu m$ Ni = B5 Plating:

Part Number (for IC-use)

IC149 272 - *29 - BB5

Series No. No. of Contact Pins

Positioning Pins:

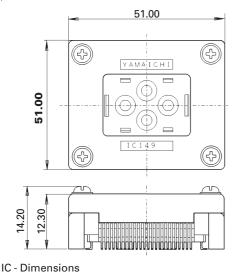
0 = Without Pins

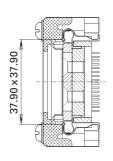
1 = With Pins

Contact Plating: B5 = Au over Ni

Compatible Emulation-Adapter not available

Outline Socket Dimensions (Reference Only)

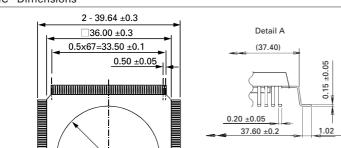


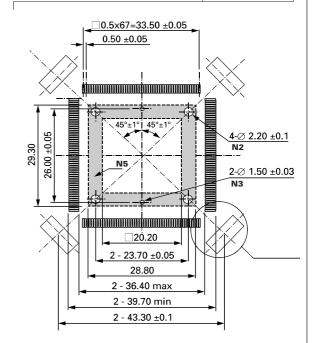


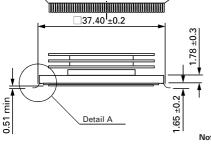
Socket PCB-Layout

- 1. Ensure a clean contact area. Fluxes, dust and other impurifications
- 2. This Socket is not for automatic production. It is particulary suitable for the development of software stored in ROM and for testing LSI-IC's.
- 3. Careful attention must be taken when fixing the Socket, since it is entirely made from thermoplastic material. If the max, torque is exceeded, the Socket will be damaged beyond repair.
- 4. If using the Socket with an Adapter, please use the gold-plated Socket

Top View from Socket







- N1: Metal soldering Tab Clip. Socket may be stabilized by soldering (Reflow) in these 4 areas
- N2: These holes are only necessary when fixing the Socket with screws.
- N3: These holes are only necessary for use with positioning pins.
- No conduits within this hatched area.



IC149 Series (SMT)

QFP/TQFP - 208 Pins (52x52) 0.5mm pitch

Specifications

Insulation Resistance: $500 M\Omega$ at 150V DC

Withstanding Voltage: $100V_{\rm eff}$ to $700V_{\rm eff}$ for 1 minute Contact Resistance: $30m\Omega$ max. at 10mA and 20mV

Operating Temp. Range: -25°C to +85°C 220°C for 60 seconds Reflow-soldering Temp.: Mating Cycles: 20 insertions maximum

Solvent Durability:

Allowable Torque (max.): - for 1-time screw connection = max 0.147 Nm

- for repetitive screw connection = min 0.078 Nm

max 0.098 Nm

Materials and Finish

Housing: Polyphenylenesulfide (PPS) glass filled UL94V-0

Contact: Beryllium Copper (BeCu)

Au $0.3\mu m$ min. over $2.5 \sim 4.5\mu m$ Ni = B5

Part Number (for IC-use)

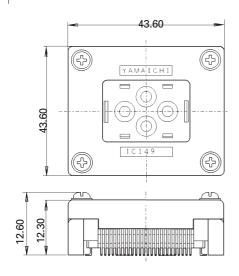
B5 = Au over Ni

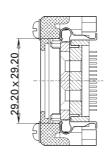
not available

IC149 208 - *61 - B5 Series No. No. of Contact Pins Positioning Pins: 0 = Without Pins 1 = With Pins Contact Plating:

Compatible Emulation-Adapter

Outline Socket Dimensions (Reference Only)





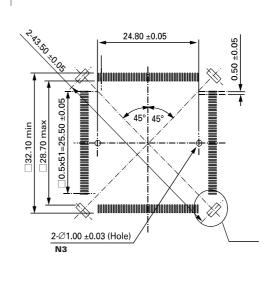
- 1. Ensure a clean contact area. Fluxes, dust and other impurifications may cause corrosion and contact problems.
- 2. This Socket is not for automatic production. It is particulary suitable for the development of software stored in ROM and for testing LSI-IC's.
- 3. Careful attention must be taken when fixing the Socket, since it is entirely made from thermoplastic material. If the max, torque is exceeded, the Socket will be damaged beyond repair.
- 4. If using the Socket with an Adapter, please use the gold-plated Socket

IC - Dimensions

□30.60 ±0.3 28.00 ±0.2 0.5x51=25.50 ±0.1 0.5 ±0.05 i i na annanananananan kanananananananan 4.07 max 0.50 ±0.2 0.22 ±0.05 N1: Metal soldering Tab Clip. Socket may be stabilized by soldering (Reflow) in these 4 areas N3: These holes are only necessary for use with positioning pins

Socket PCB-Layout

Top View from Socket





Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Yamaichi Electronics:

IC149-176-066-B5 IC149-208-061-B5